

ASSIGNMENT CO2

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1. Explain briefly about the power / average power dissipated by a CMOS inverter over one entire time period.

A. The average power dissipated by a CMOS inverter over one entire time period consists of three components:-

→ static power dissipation (P_s)

→ Dynamic power dissipation (P_D)

→ short circuit power dissipation (P_{sc})

∴ Total power dissipation

$$P_T = P_s + P_D + P_{sc}$$

where,

$$P_D = C_L V_{DD}^2 f_p$$

$$P_s = I_{leakage} \times V_{DD}$$

$$P_{sc} = \frac{K}{2} (V_{DD} - 2V_t)^3 \frac{t_{rf}}{t_p}$$

$$\therefore P_T = C_L V_{DD}^2 f_p + I_{leakage} \times V_{DD} + \frac{K}{2} (V_{DD} - 2V_t)^3 \frac{t_{rf}}{t_p}$$

2. Explain the advantages of linear load NMOS inverter over saturated load NMOS inverter.

A. Advantages:-

→ Low Power consumption:- Reduces static power dissipation compared to saturated load.

→ Better Noise margins: Provides improved noise immunity and stable operation.

→ Higher voltage swing: Allows output voltage to reach closer to V_{DD} .

- Low static Power Dissipation: minimizes unnecessary power loss in steady state.
- Faster switching speed: Avoids deep saturation, leading to quick transitions.
- Simple Fabrication: Uses depletion-mode NMOS, making circuit design easier.

3. A digital circuit has a known propagation delay of 10 ns. Using the delay estimation formula, calculate the critical path delay for a combinational circuit with 5 logic gates connected in series.

A. Given,

Propagation delay per gate = 10 ns

Number of gates in series = 5

$$\begin{aligned} \rightarrow \text{Critical path delay} &= \text{Number of gates} \times \text{Propagation delay per gate} \\ &= 5 \times 10 \text{ ns} \\ &= 50 \text{ ns.} \end{aligned}$$

4. Apply the concept of logical effort to size the transistors in a CMOS circuit for minimizing delay. Assume a specific fan-out.

A. Logical effort is a technique used to size transistors in CMOS circuit for minimum delay by balancing the drive strength of gates.

1. Fanout (H) → ratio of output load capacitance to input capacitance.

• Logical effort (G) → A measure of how much harder a gate drives compared to an inverter.

$$\text{Inverter} = g = 1, \text{ NAND2} = g = 4/3, \text{ NOR2} = g = 5/3$$

Path Effort (F) → The product of logical effort and electrical effort.

2. Path Effort

$$F = G \times H$$

3. Optimal No. of stages (N):

$$N = \log_4(F)$$

4. Optimal Gate Effort:

$$f = F^{1/N}$$

5. Determine Transistor sizes

- Assign input capacitance c_{in} to each stage.

Example:

Let, consider circuit with three stages & $H = 4$

1. $G = (1) \times (4/3) \times (5/3) = 20/9$

2. $F = G \times H = 20/9 \times 4 = 80/9$

3. $N = \log_4(80/9) \approx 3$

4. $f = F^{1/N} = (80/9)^{1/3} \approx 2.3$

5. To maintain equal effort

Inverter size $c_{in} = 1$

NAND2 size $c_{in} = 2.3$

NOR2 size $c_{in} = (2.3)^2 = 5.3$

5. For a CMOS circuit operating at a specific frequency 100MHz and supply voltage of 15V. Calculate the dynamic power dissipation. Consider the gate capacitance as 10nF.

A. Given,

$$f_p = 100\text{MHz} = 100 \times 10^6 \text{ Hz}$$

$$V_{DD} = 15\text{V}$$

$$C_L = 10\text{nF} = 10 \times 10^{-9} \text{ F}$$

$$\begin{aligned} \Rightarrow \text{Dynamic power dissipation} &= C_L V_{DD}^2 f_p \\ &= (10 \times 10^{-9}) (15)^2 (100 \times 10^6) \\ &= 1000 \times 225 \\ &= 225 \text{ KW} \end{aligned}$$

6. A scaled-down CMOS reduces transistor area by a factor of $1/2$. Calculate the resulting improvement in the transistor discussions.

A. Given

$$\text{scaling factor} = 1/2$$

In CMOS, transistor area is \propto to square of the feature size

$$\boxed{A \propto L^2}$$

$$A_{\text{new}} = \frac{1}{2} A_{\text{old}}$$

$$L_{\text{new}}^2 = \frac{1}{2} L_{\text{old}}^2$$

$$L_{\text{new}} = \frac{L_{\text{old}}}{\sqrt{2}}$$

$$L_{\text{new}} \approx 0.707 L_{\text{old}}$$

∴ Transistor length and width are reduced by a factor of $0.707 (1/\sqrt{2})$. This results in smaller transistor dimensions, leading to improved switching speed, reduced capacitance and lower power consumption.

7. Explain the dynamic behavior of a CMOS inverter during switching.

A. The dynamic behaviour of a CMOS inverter refers to how the output voltage transitions between logic high and logic low when the input changes. The switching process involves:

1. charging phase (Low-to-High):

The process where the output voltage transitions from low (0V) to High (V_{DD}) as the load capacitance charges through the PMOS transistor.

2. Discharging phase (High-to-Low):

The process where the output voltage transitions from High (V_{DD}) to Low (0V) as the load capacitance discharges through the NMOS transistor.

3. Propagation delay:

Time taken for output to respond to input.

$$t_p = \frac{t_{AH} + t_{PHL}}{2}$$

4. Dynamic Power Dissipation:

The power consumed due to switching activity.

$$P_d = C_L V_{DD}^2 f_p.$$

8. Design a CMOS circuit to drive a capacitive load of 40ff. The circuit consists of 4 stages with a combined signal logical effort of 2. Calculate the optimal stage effort and determine the size of each stage to minimize delay.

A. Given,

$$C_L = 40\text{ff}, N = 4, G = 2$$

1. Path effort:

$$F = G \times H$$

Assume the initial gate has an input capacitance of C_{in} :

$$H = \frac{C_L}{C_{in}}$$

$$\therefore F = 2 \times \frac{C_L}{C_{in}}$$

2. Optimal stage effort:

$$f = F^{1/N}$$

$$f = \left(2 \times \frac{C_L}{C_{in}} \right)^{1/4} = \left(2 \times \frac{40}{C_{in}} \right)^{1/4}$$

Let, $C_{in} = 5\text{ff}$

$$f = \left(2 \times \frac{40}{5} \right)^{1/4}$$

$$f = (16)^{1/4}$$

$$f = (2^4)^{1/4}$$

$$f = 2$$

3. Gate size:

$$\rightarrow C_1 = f \times C_{in} = 2 \times 5 = 10 \text{ fF}$$

$$\rightarrow C_2 = f \times C_1 = 2 \times 10 = 20 \text{ fF}$$

$$\rightarrow C_3 = f \times C_2 = 2 \times 20 = 40 \text{ fF}$$

$$\rightarrow C_4 = f \times C_3 = C_L = 40 \text{ fF}$$

$\therefore C_4$ matches with C_L

To minimize delay, the transistor sizes should be increased by a factor of 2 per stage.

4. For a clock signal routed through an interconnect with $R = 50 \Omega$ and $C = 200 \text{ fF}$, calculate the propagation delay using the lumped RC model.

A. Given,

$$R = 50 \Omega, C = 200 \text{ fF} = 200 \times 10^{-15} \text{ F}$$

Propagation delay (RC model):

$$t_p = 0.69 \times R \times C$$

$$t_p = 0.69 \times 50 \times 200 \times 10^{-15}$$

$$t_p = 0.69 \times 10000 \times 10^{-15}$$

$$t_p = 6900 \times 10^{-15}$$

$$t_p = 6.9 \times 10^{-12}$$

$$t_p = 6.9 \text{ ps}$$

10. A circuit has a setup time of 1.5 ns , hold time of 0.5 ns , and clock period of 4 ns . calculate the timing margin for correct operation.

A. Given

$$t_{\text{setup}} = 1.5\text{ ns}$$

$$t_{\text{hold}} = 0.5\text{ ns}$$

$$T = 4\text{ ns}$$

margin for setup time:

The data must arrive at least t_{setup} before next clock edge.

$$T - t_{\text{setup}}$$

$$= 4 - 1.5$$

$$= 2.5\text{ ns}$$

margin for hold time:

The data must remain stable for at least t_{hold} after clock edge.

$$\text{Data Arrival Time} - t_{\text{hold}}$$

The circuit delay should be greater than t_{hold} for correct operation.

11. For a resistive-load inverter with $R_L = 5\text{ k}\Omega$, Calculate the propagation delay if the load capacitance is 20 fF .

A. Given,

$$R_L = 5\text{ k}\Omega$$

$$C_L = 20\text{ fF} = 20 \times 10^{-15}\text{ F}$$

→ Propagation Delay for resistive-load inverter:

$$t_p = 0.69 \times R_L \times C_L$$

$$t_p = 0.69 \times 5 \times 10^3 \times 20 \times 10^{-15}$$

$$t_p = 0.69 \times 5000 \times 20 \times 10^{-15}$$

$$t_p = 0.69 \times 100000 \times 10^{-15}$$

$$t_p = 0.69 \times 10^{-10}$$

$$t_p = 69 \times 10^{-12}$$

$$t_p = 69 \text{ ps}$$

12. For a technology scaling factor of 0.707, calculate the impact on transistor area, delay, and power dissipation for a CMOS inverter with initial dimensions of $1 \mu\text{m}$.

A. Given,

$$S = 0.707$$

Initial dimensions = $1 \mu\text{m}$

⇒ Impact on transistor area:

we know that

$$A' = A \times S^2$$

$$A' = (1 \times 1) \times (0.707)^2$$

$$A' = 1 \times 0.5$$

$$A' = 0.5 \mu\text{m}^2$$

Area reduces by 50%.

⇒ Impact on Propagation Delay:

$$t_p' = t_p \times s$$

$$t_p' = t_p \times 0.707$$

$$t_p' \approx 0.707 t_p$$

$$t_p \propto R \propto C$$

$$t_p' = R' \times C'$$

$$t_p' = \left(R \times \frac{1}{s}\right) (C \times s)$$

$$t_p' = R \times C \times s$$

$$t_p' = t_p \times s$$

Delay reduces by 29.3%.

⇒ Impact on Power dissipation:

Dynamic ÷

$$P_d = C V^2 f$$

$$C' = C \times s, V' = V \times s, f' = f \times \frac{1}{s}$$

$$P_d' = C V^2 f$$

$$= (C \times s) (V \times s)^2 (f \times \frac{1}{s})$$

$$= C V^2 f \times \cancel{s} \times s^2 \times \frac{1}{s}$$

$$P_d' = P_d \times s^2$$

$$P_d' = P_d \times (0.707)^2$$

$$P_d' = P_d \times 0.354$$

reduces by 64.6%.

$$\% \text{ Reduction} = \left(1 - \frac{P_d'}{P_d}\right) \times 100$$

$$= (1 - 0.354) \times 100$$

$$= 0.646 \times 100$$

$$= 64.6\%$$

static:

$$P_S = V \times I_{\text{leak}}$$

$$V' = V \times S, I'_{\text{leak}} = I_{\text{leak}} \times S$$

$$P'_S = (V \times S) \times (I_{\text{leak}} \times S)$$

$$P'_S = V \times I_{\text{leak}} \times S^2$$

$$P'_S = P_S \times S^2$$

$$P'_S = P_S \times (0.707)^2$$

$$P'_S = P_S \times 0.5$$

$$\% \text{ Reduction} = \left(1 - \frac{P'_S}{P_S}\right) \times 100$$

$$= (1 - 0.5) \times 100$$

$$= 0.5 \times 100$$

$$= 50\%$$

13. Design a resistive-load inverter with $R_L = 10 \text{ k}\Omega$, $V_{DD} = 5 \text{ V}$,

$V_T = 1 \text{ V}$. Calculate the voltage transfer characteristic (VTC)

and determine the noise margins.

A. Given

$$R_L = 10 \text{ k}\Omega, V_{DD} = 5 \text{ V}, V_T = 1 \text{ V}.$$

1. VTC:-

Case 1: Cutoff Region

When $V_{in} < V_T$, the NMOS is off, that means there is no current flows through R_L , the output remains at V_{DD} .

$$V_{out} = V_{DD} = 5 \text{ V}.$$

case 2: Linear region ($V_T \leq V_{in} \leq V_{out} + V_T$)

The NMOS turns ON, but the drain-source vol is small,

$$I_D = k [2(V_{in} - V_T)(V_{out} - V_{out}^2)]$$

current through load-resistor:

$$I_D = \frac{V_{DD} - V_{out}}{R_L}$$

case-3: Saturation region ($V_{in} > V_{out} + V_T$)

The NMOS is fully ON.

$$I_D = k(V_{in} - V_T)^2$$

current through load-resistor:

$$I_D = \frac{V_{DD} - V_{out}}{R_L}$$

By equating, we get the output voltage for large V_{in} .

2. Noise margin

It determines how much noise the inverter can tolerate while maintaining correct operation,

$$NML = V_{IL} - 0V$$

$$NMH = 5V - V_{IH}$$

14. Design a CMOS circuit to drive a capacitive load of 40fF. The circuit consists of 4 stages with a combined logical effort of 2. Calculate the optimal stage effort and determine the size of each stage to minimize delay.

A. Given,

$$C_L = 40\text{fF}, N = 4, G = 2$$

1. Path Effort

$$F = G \times H$$

$$F = 2 \times \frac{C_L}{C_{in}}$$

$$F = 2 \times \frac{40}{1} \quad (\because C_{in} = 1)$$

$$F = 80$$

2. Optimal stage effort

$$f = F^{1/N} = (80)^{1/4} = 3.17$$

3. Size

$$h = \frac{C_{out}}{C_{in}} = f$$

$$C_4 = C_L = 40\text{fF}$$

$$C_3 = \frac{C_4}{f} = \frac{40}{3.17} = 12.6\text{fF}$$

$$C_2 = \frac{C_3}{f} = \frac{12.6}{3.17} = 4.0\text{fF}$$

$$C_1 = \frac{C_2}{f} = \frac{4.0}{3.17} = 1.26\text{fF}$$

Each stage should have a size ratio of 3.17 relative to the previous stage.